

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC011N03LS	**Issued**	4. July 2019
MA#	MA005348836		
Package	PG-TDSON-8-50	**Weight***	106.79 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.077	1.01	1.01	10082	10082
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		128	
	non noble metal	zinc	7440-66-6	0.055	0.05		511	
	non noble metal	iron	7439-89-6	1.090	1.02		10210	
	non noble metal	copper	7440-50-8	44.271	41.47	42.55	414569	425418
wire	noble metal	gold	7440-57-5	0.038	0.04	0.04	353	353
encapsulation	organic material	carbon black	1333-86-4	0.084	0.08		790	
	plastics	epoxy resin	-	3.881	3.63		36343	
	inorganic material	silicondioxide	60676-86-0	38.220	35.79	39.50	357900	395033
leadfinish	non noble metal	tin	7440-31-5	1.264	1.18	1.18	11834	11834
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	272	272
solder	noble metal	silver	7440-22-4	0.036	0.03		339	
	non noble metal	tin	7440-31-5	0.072	0.07		677	
	non noble metal	lead	7439-92-1	1.338	1.25	1.35	12527	13543
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005	0.00		43	
	non noble metal	zinc	7440-66-6	0.018	0.02		172	
	non noble metal	iron	7439-89-6	0.368	0.34		3443	
	non noble metal	copper	7440-50-8	14.930	13.98	14.34	139807	143465
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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